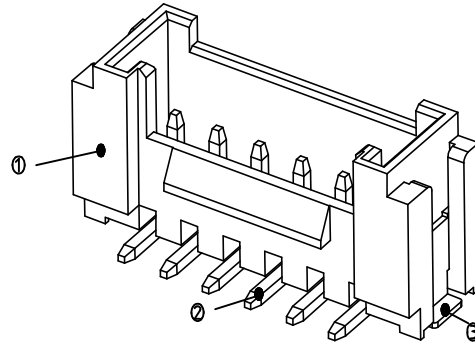
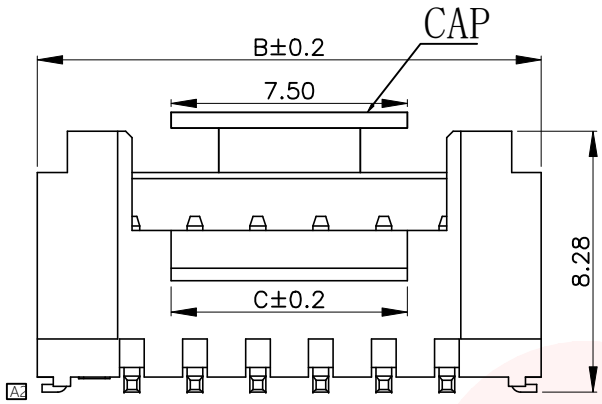
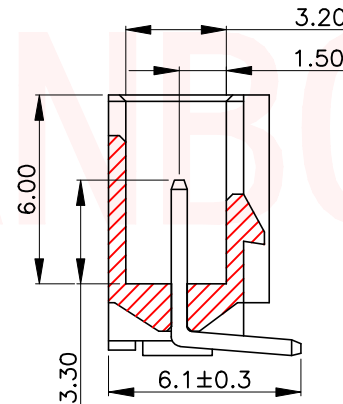
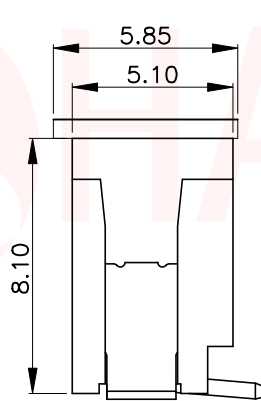




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



	02P-10P	0.10	MAX
	11P-16P	0.12	MAX

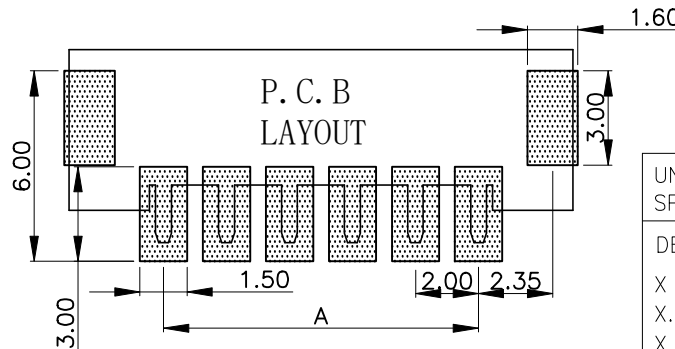
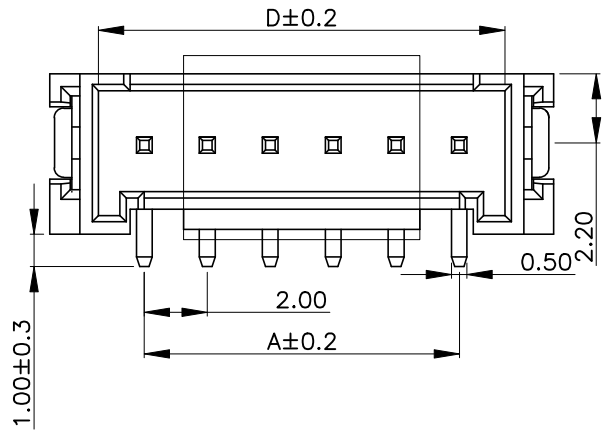


SPECIFICATIONS

- 1、Current Rating: 2A AC, DC
- 2、Voltage Rating: 250V AC, DC
- 3、Temperatuer Range: -25°C~+85°C
- 4、Contact Resistance: 20mΩ Max
- 5、Insulation Resistance: 1000MΩ Min
- 6、Withstanding Voltang: 1000V AC/minute
- 7、Material: Wafer LCP, UL94V-0
PIN Brass Tin-plated
Solder Brass Tin-plated

TABLE:

CSG PART NO.	Dimension mm			
	A	B	C	D
WAFER-HY200L-2A	2.00	8.00	2.50	4.90
WAFER-HY200L-3A	4.00	10.00	2.50	6.90
WAFER-HY200L-4A	6.00	12.00	5.00	8.90
WAFER-HY200L-5A	8.00	14.00	7.00	10.90
WAFER-HY200L-6A	10.00	16.00	9.00	12.90
WAFER-HY200L-7A	12.00	18.00	11.00	14.90
WAFER-HY200L-8A	14.00	20.00	13.00	16.90
WAFER-HY200L-9A	16.00	22.00	15.00	18.90
WAFER-HY200L-10A	18.00	24.00	17.00	20.90
WAFER-HY200L-11A	20.00	26.00	19.00	22.90
WAFER-HY200L-12A	22.00	28.00	21.00	24.90
WAFER-HY200L-13A	24.00	30.00	23.00	26.90
WAFER-HY200L-14A	26.00	32.00	25.00	28.90
WAFER-HY200L-15A	28.00	34.00	27.00	30.90
WAFER-HY200L-16A	30.00	36.00	29.00	32.90



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X :±0.25	X :±2°
X.X :±0.20	X.X :±1°
X.XX :±0.15	



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	WAFER HY 2.0立贴 SMT TYPE			
DWN	xiong	PART NO. WAFER-HY200L-NA		
CHKD	lee	SCALE:1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET:10F 1	REV: A4
CUSTOMER COPY				